

General Description

The Sanrise SRC65R380S is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC65R380S break down voltage is 650V and it has a high rugged avalanche characteristics. The SRC65R380S is available in TO-252 ,TO-220F, and TO-263-2 packages .

Features

- Ultra Low $R_{DS(ON)} = 380m\Omega @ V_{GS} = 10V$.
- $V_{ds}@T_{jmax}=700v$
- Ultra Low Gate Charge, $Q_g=17nC$ typ.
- Fast switching capability
- Robust design with better EAS performance
- EMI Improved Design
- Non-automotive Qualified

Application

- TV Power
- High Performance Charger / Adapter

Symbol

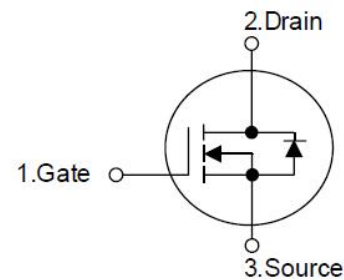


Figure 1 Symbol of SRC65R380S

Package Type

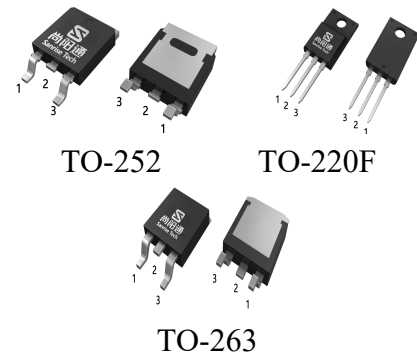
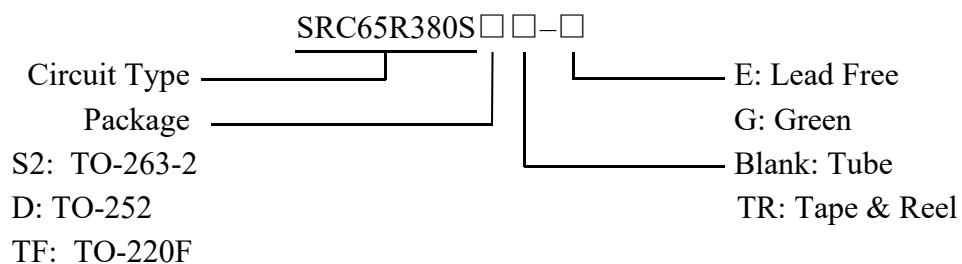


Figure 2 Package Types of SRC65R380S

Ordering Information



Package	Part Number	Marking ID	Packing Type
TO-252	SRC65R380SDTR-G	SRC65R380SDG	Tape & Reel
TO-263-2	SRC65R380SS2TR-G	SRC65R380SS2G	Tape & Reel
TO-220F	SRC65R380STF-G	SRC65R380STFG	Tube

Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	650	V
Gate-Source Voltage (static)		V_{GSS}	±20	V
Gate-Source Voltage (dynamic), AC ($f > 1$ Hz)		V_{GSS}	±30	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$ (Note2)	I_D	12.6	A
	$T_C = 100^\circ\text{C}$		8.0	
	$T_C = 125^\circ\text{C}$		5.6	
Pulsed Drain Current (Note 3)		I_{DM}	37.8	A
Avalanche Energy, Single Pulse (Note 4)		E_{AS}	109	mJ
Avalanche Energy, Single Pulse (Note 5)		E_{AS}	356	mJ
Avalanche Energy, Repetitive (Note 3)		E_{AR}	0.1	mJ
Avalanche Current, Repetitive (Note 3)		I_{AR}	1.8	A
Continuous Diode Forward Current		I_S	12.6	A
Diode Pulse Current		$I_{S,PULSE}$	37.8	A
Power Dissipation ($T_C = 25^\circ\text{C}, TO-220F$)		P_{tot}	32	W
Power Dissipation ($T_C = 25^\circ\text{C}, TO-252, TO-263-2$)		P_{tot}	73	W
MOSFET dv/dt Ruggedness, $V_{DS} \leq 480V$		dv/dt	120	V/ns
Reverse Diode dv/dt , $V_{DS} \leq 480V, I_{SD} \leq I_D$		dv/dt	50	V/ns
Operating Junction Temperature		T_J	150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 to 150	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	$^\circ\text{C}$

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- Duty=0.70.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS} = 1.8A, V_{DD} = 60V, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$. Finish goods test condition.
- $I_{AS} = 3.25A, V_{DD} = 60V, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$. Typical Eas.

Thermal Resistance

Parameter		Symbol	Min	Typ	Max	Unit
Thermal resistance, Junction-to-Case	TO-220F	R_{thJC}			3.8	$^\circ\text{C} / \text{W}$
	TO-252				1.7	
	TO-263-2				1.7	
Thermal resistance, Junction-to-Ambient	TO-220F	R_{thJA}			70	$^\circ\text{C} / \text{W}$
	TO-252				62	
	TO-263-2				62	

Electrical Characteristics

$T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	650			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=650V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=30V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-30V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.7	3.5	4.3	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=5.0A$		240	380	mΩ
Gate Resistance	R_G	f=1MHz, Open Drain		4.3		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=400V, V_{GS}=0V,$		759		pF
Output Capacitance	C_{OSS}	f=100KHz		25		
Effective output capacitance, energy related ^{NOTE7}	$C_{O(er)}$	$V_{GS}=0V,$ $V_{DS}=0\dots 400V$		38		pF
Effective output capacitance, time related ^{NOTE8}	$C_{O(tr)}$			186		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=5.0A$ $R_G=30\Omega, V_{GS}=10V$		41		ns
Rise Time	t_r			14		
Turn-off Delay Time	$t_{d(off)}$			74		
Fall Time	t_f			14		
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DD}=400V, I_D=5.0A$ $V_{GS}=0$ to 10V		4.2		nC
Gate to Drain Charge	Q_{gd}			6.5		
Gate Charge Total	Q_g			17		
Gate Plateau Voltage	$V_{plateau}$			6.0		V
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=5.0A$		0.83	1.1	V
Reverse Recovery Time	t_{rr}	$V_R=400V, I_F=5.0A$ $dI_F/dt=100A/\mu s$		218		ns
Reverse Recovery Charge	Q_{rr}			2.3		μC
Peak Reverse Recovery Current	I_{rrm}			21		A

Note:

- $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 400V
- $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 400 V

Typical Performance Characteristics

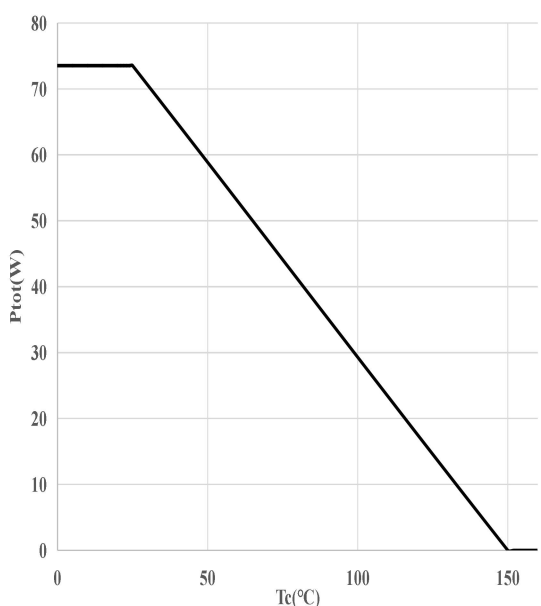
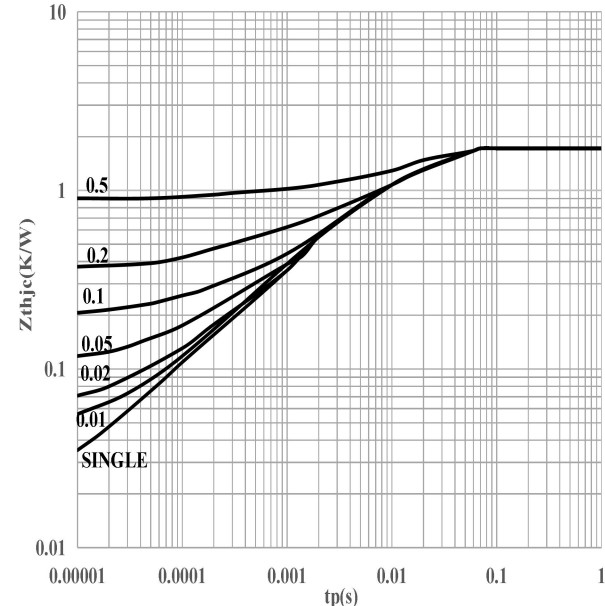
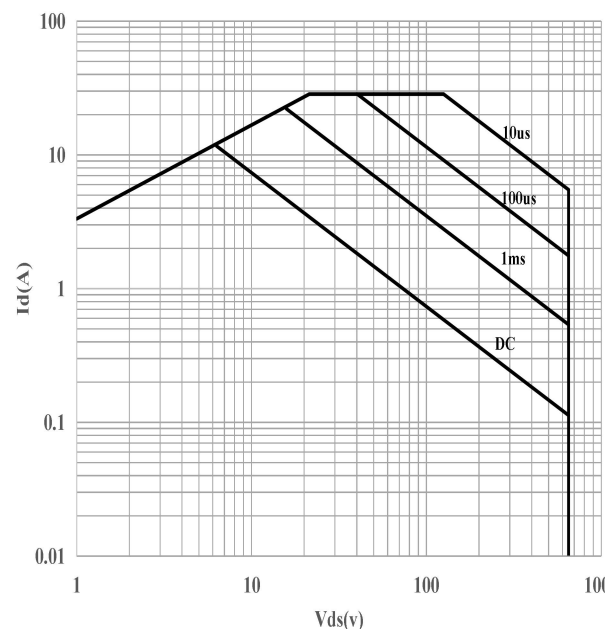
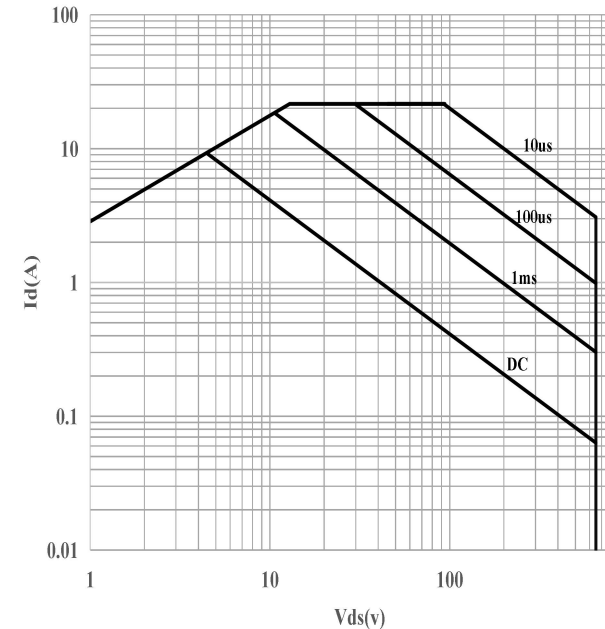
<p>Figure 3: Power Dissipation</p>  <p>$P_{tot} = f(T_c)$</p>	<p>Figure 4: Max. Transient Thermal Impedance</p>  <p>$Z_{th(jc)} = f(t_p)$; parameter: $D = t_p/T$</p>
<p>Figure 5: Safe Operating Area</p>  <p>$I_D = f(V_{DS})$; $T_c = 25^\circ\text{C}$; $V_{GS} > 7\text{V}$; parameter t_p</p>	<p>Figure 6: Safe Operating Area</p>  <p>$I_D = f(V_{DS})$; $T_c = 80^\circ\text{C}$; $V_{GS} > 7\text{V}$; parameter t_p</p>

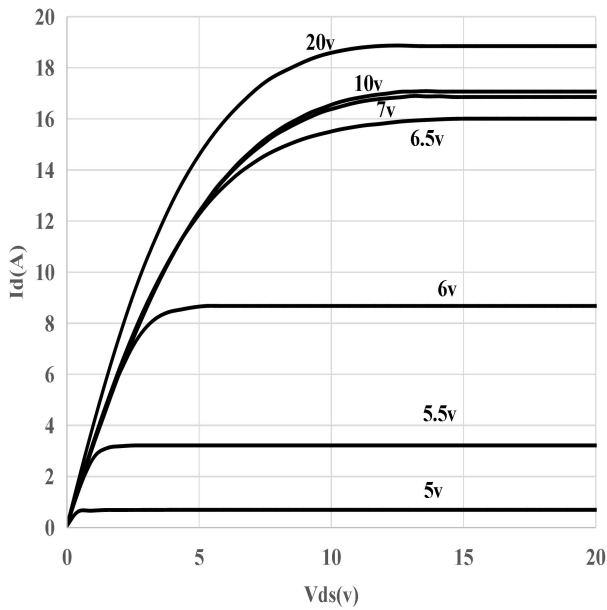
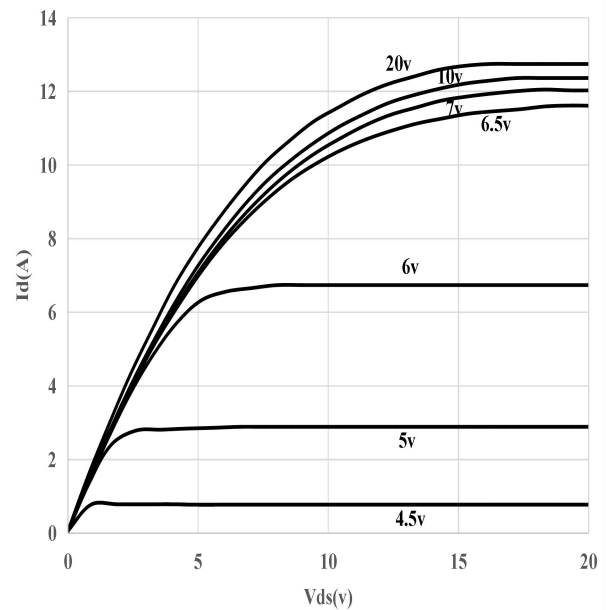
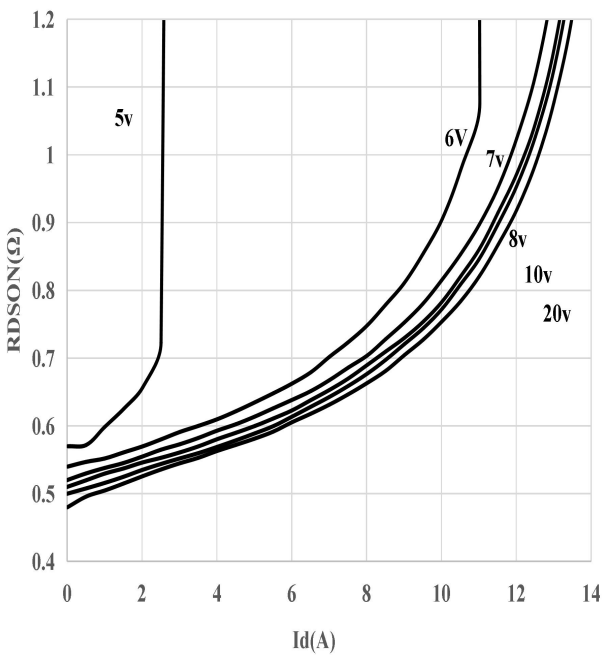
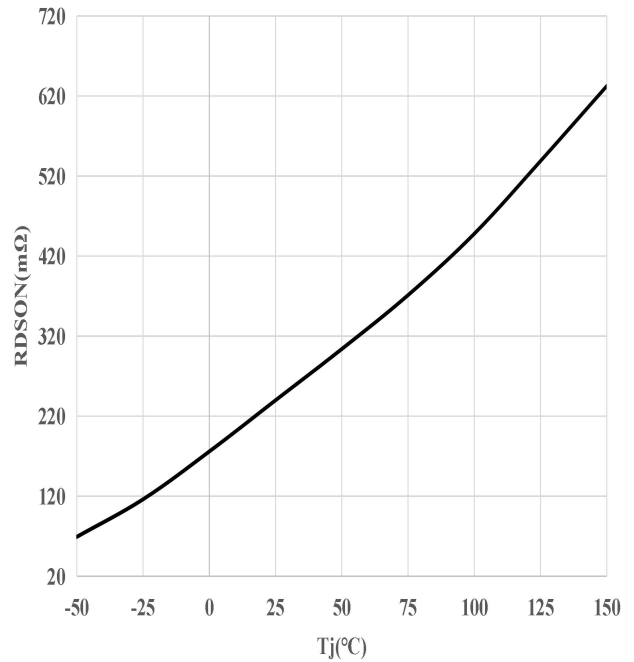
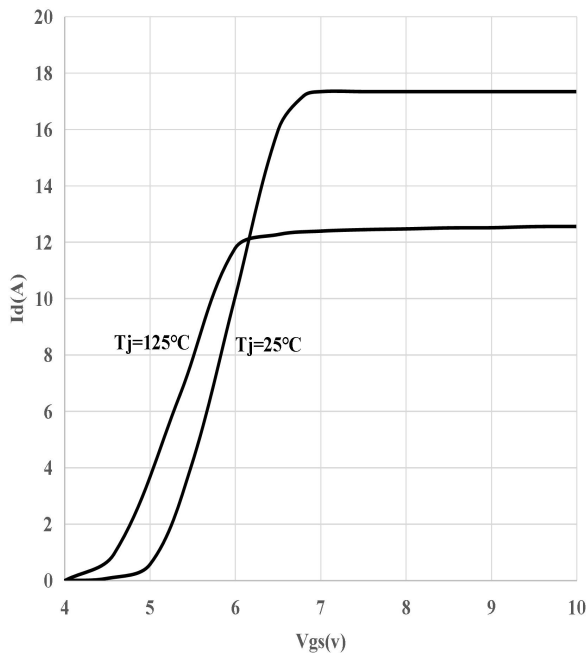
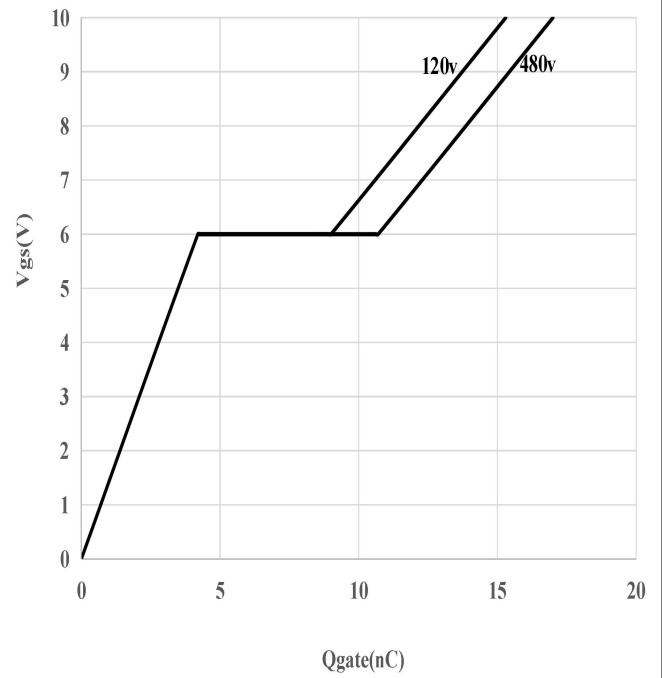
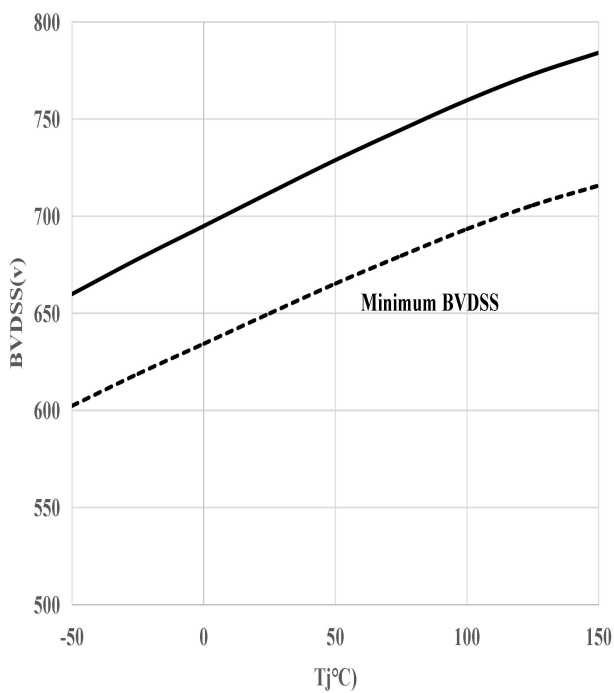
Figure 7: Typ. Output Characteristics

 $I_D = f(V_{DS}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 8: Typ. Output Characteristics

 $I_D = f(V_{DS}); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 9: Typ. Drain-Source On-State Resistance

 $R_{DS(ON)} = f(I_D); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 10: Typ. Drain-Source On-State Resistance

 $R_{DS(ON)} = f(T_j); I_D = 5.0\text{A}; V_{GS} = 10\text{V}$

Figure 11: Typ. Transfer Characteristics


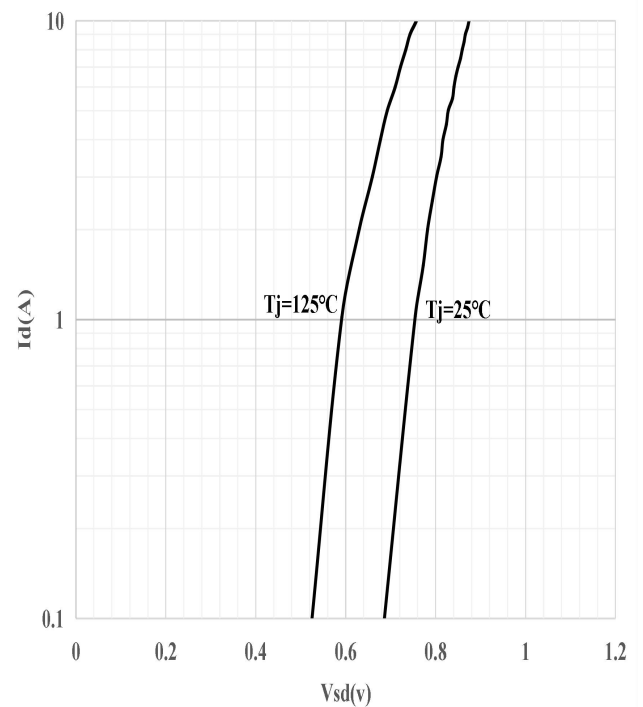
$$I_D = f(V_{GS}); V_{DS} = 20V$$

Figure 12: Typ. Gate Charge


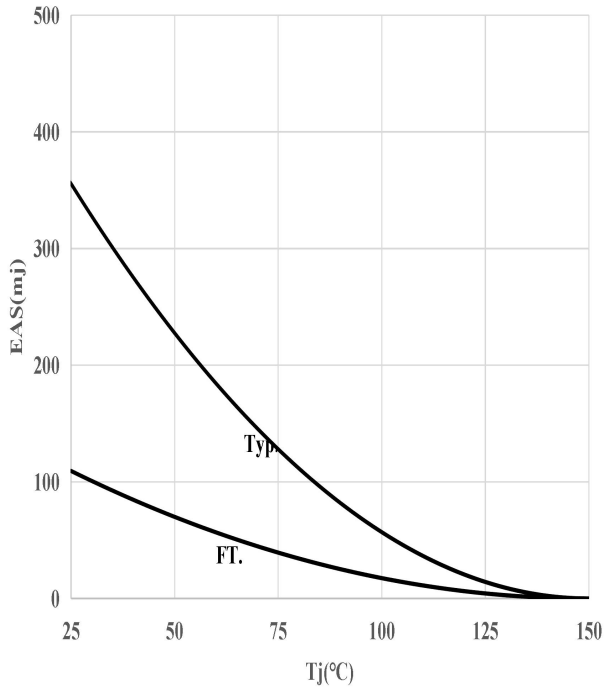
$$V_{GS} = f(Q_{gate}), I_D = 5.0A \text{ pulsed}$$

Figure 13: Drain-Source Breakdown Voltage


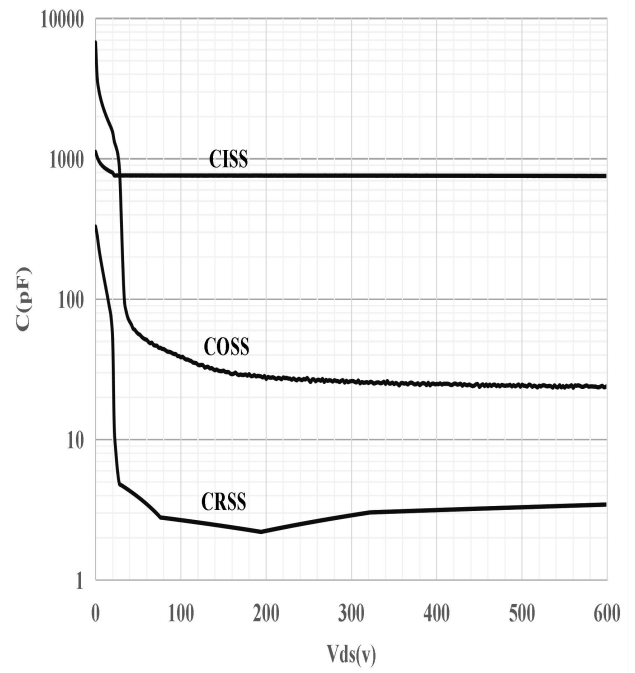
$$\text{Minimum } V_{BR(DSS)} = f(T_j); I_D = 1mA$$

Figure 14: Forward Characteristics of Reverse Diode


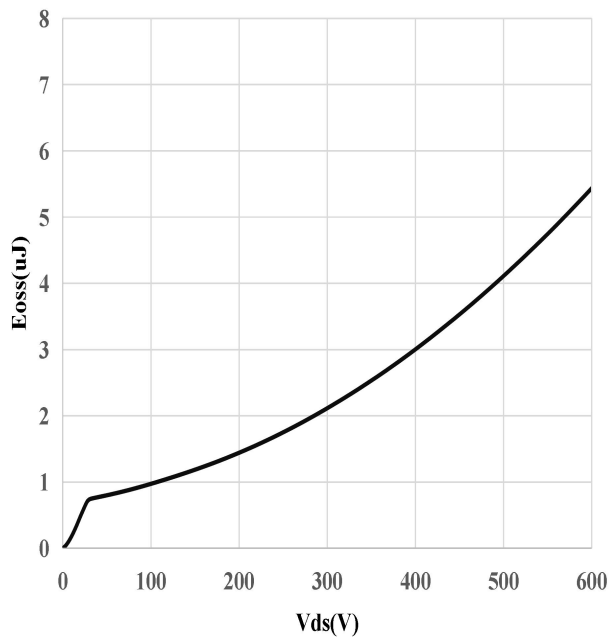
$$I_F = f(V_{SD}); \text{parameter: } T_j$$

Figure 15: Avalanche Energy


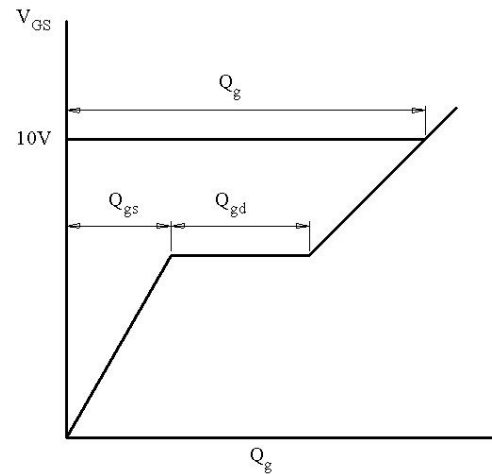
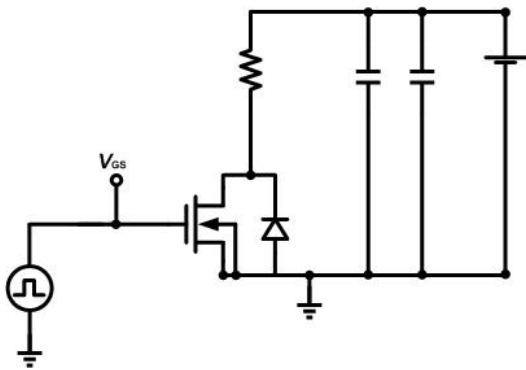
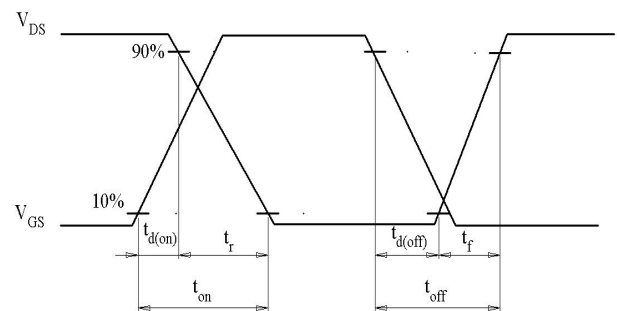
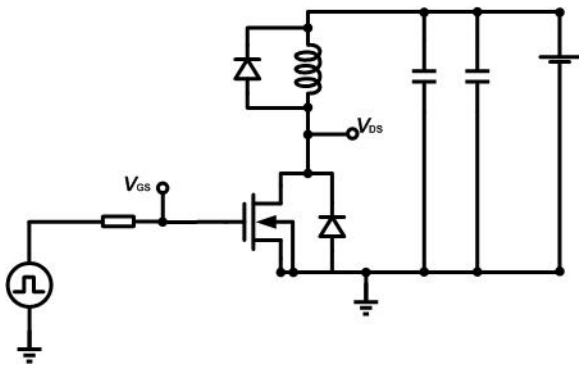
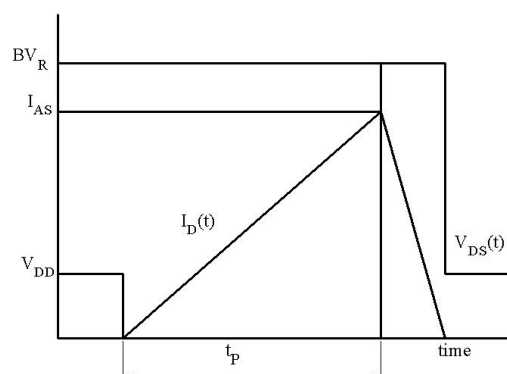
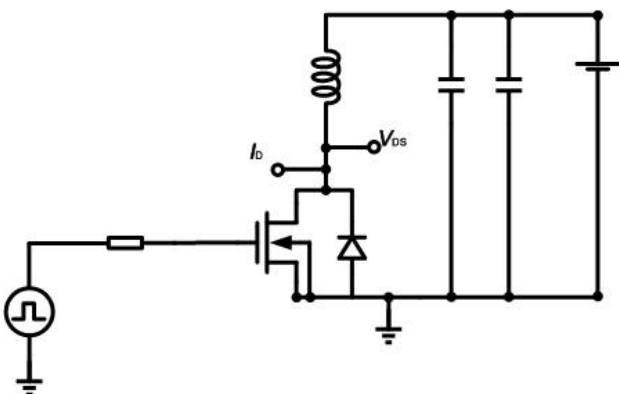
$$E_{AS}=f(T_j); V_{DD}=60V$$

Figure 16: Typ. Capacitances


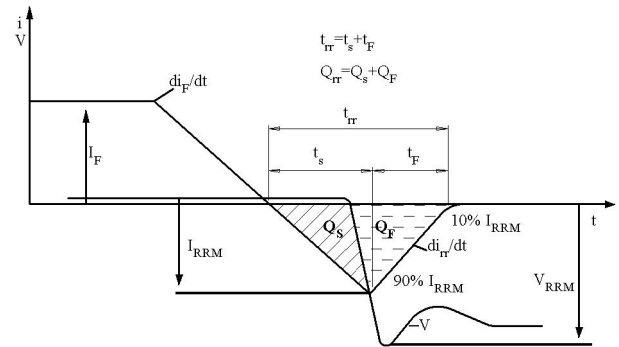
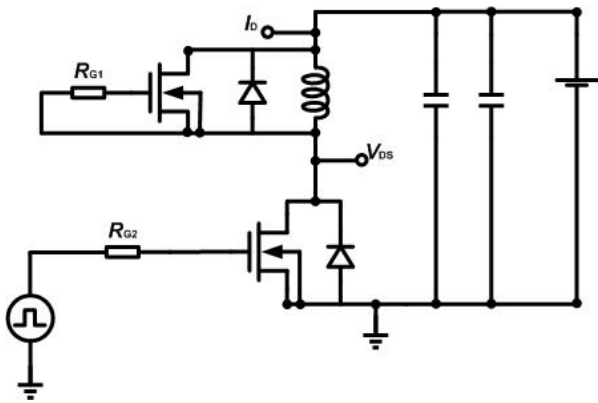
$$C=f(V_{DS}); V_{GS}=0; f=1MHz$$

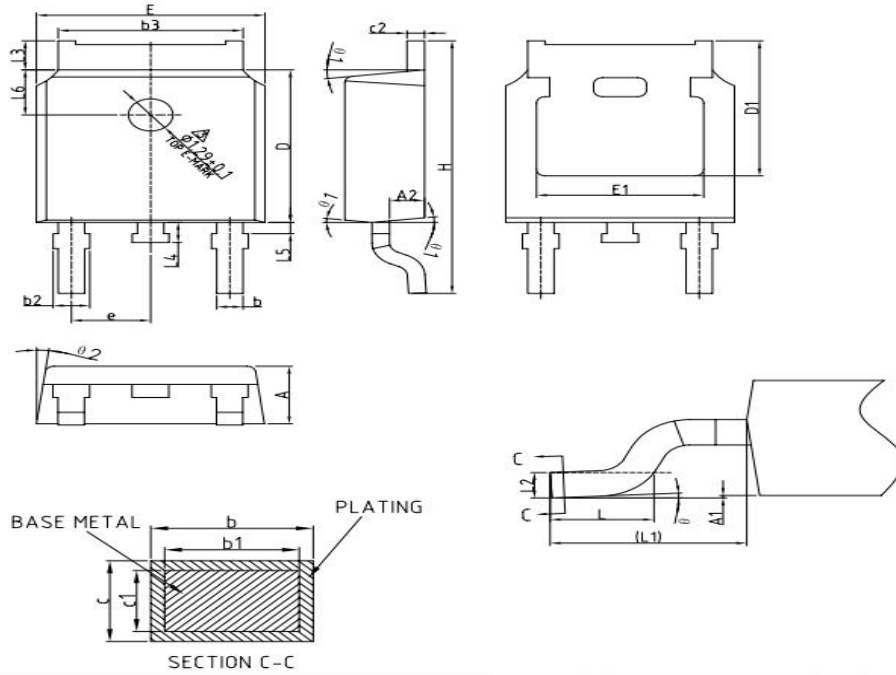
Figure 17: Coss Stored Energy


$$E_{OSS}=f(V_{DS})$$

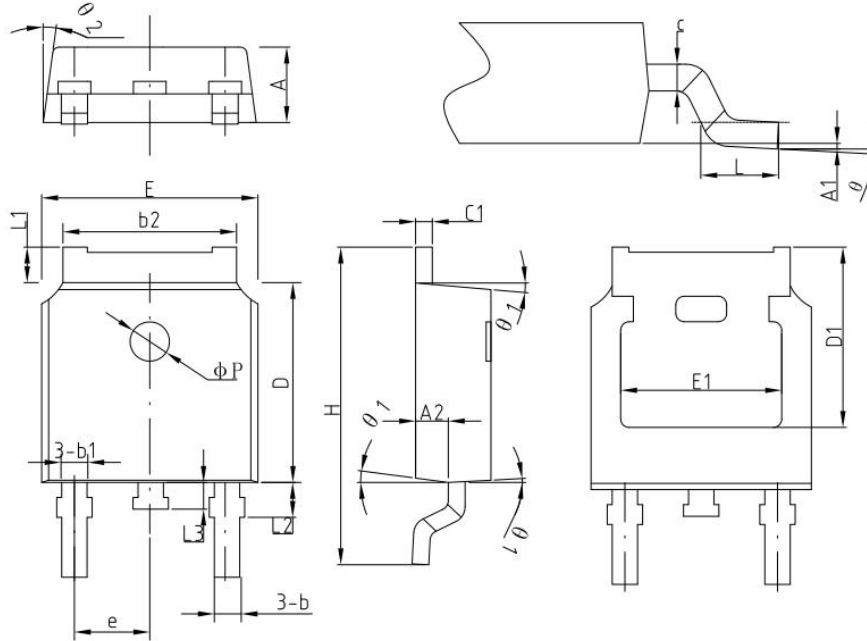
Test Circuits
1. Gate Charge Test Circuit & Waveform

2. Switch Time Test Circuit

3. Unclaimed Inductive Switching Test Circuit & Waveforms


4. Test Circuit and Waveform for Diode Characteristics

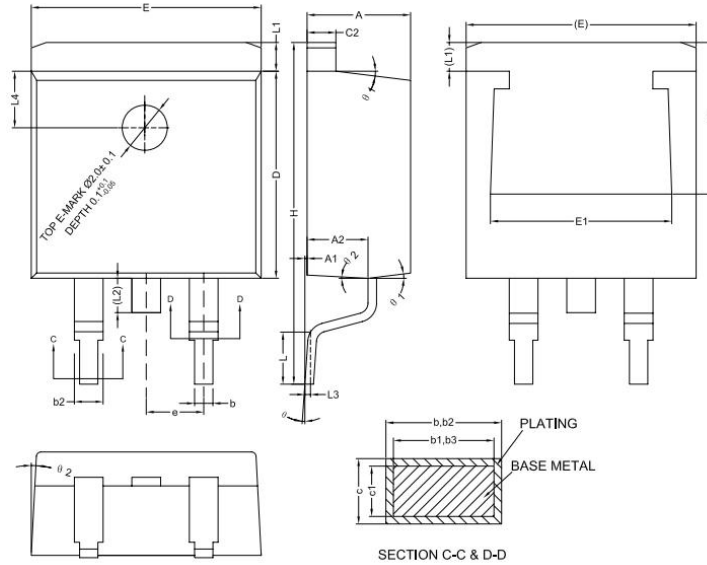


Mechanical Dimensions
TO-252 (Package 1)
Unit: mm


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0	-	0.10
A2	0.90	1.01	1.10
b	0.72	-	0.85
b1	0.71	0.76	0.81
b2	0.72	-	0.90
b3	5.13	5.33	5.46
c	0.47	-	0.60
c1	0.46	0.51	0.56
C2	0.47	-	0.60
D	6.0	6.10	6.20
D1	5.25	-	-
E	6.50	6.60	6.70
E1	4.70	-	-
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90REF		
L2	0.51BSC		
L3	0.90	-	1.25
L4	0.60	0.80	1.00
L5	0.15	-	0.75
L6	1.80REF		
Ø	0°	-	8°
Ø1	5°	7°	9°
Ø2	5°	7°	9°

Mechanical Dimensions
TO-252 (Package 2)
Unit: mm


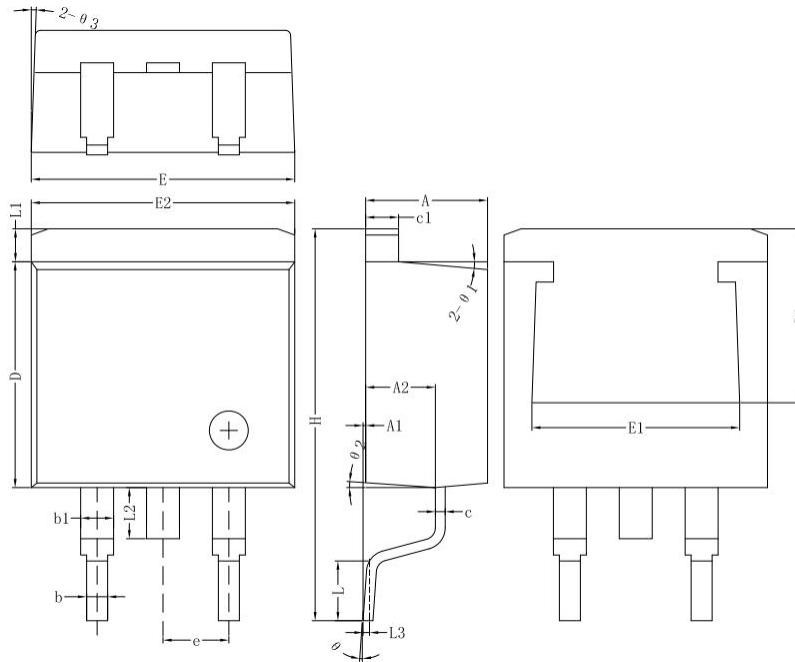
Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0	-	0.127
A2	0.90	1.01	1.10
b	0.635	0.76	0.86
b1	-	0.76	-
b2	5.2	5.33	5.46
c	0.47	0.50	0.60
c1	0.47	0.50	0.60
D	6.0	6.10	6.20
D1	-	5.30	-
E	6.50	6.60	6.70
E1	-	4.83	-
e	2.286(BSC)		
H	9.70	10.10	10.40
L	1.40	1.50	1.70
L1	0.90	-	1.25
L2	-	1.0	-
L3	-	0.8	-
φP	-	1.2	-
θ	0°	-	8°
θ1	5°	7°	9°
θ2	5°	7°	9°

Mechanical Dimensions
TO-263-2 (Package 1)
Unit: mm


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.40	4.57	4.70
A1	0.00	0.10	0.25
A2	2.59	2.69	2.79
b	0.77	-	0.90
b1	0.76	0.81	0.86
b2	1.23	-	1.36
b3	1.22	1.27	1.32
c	0.34	-	0.47
c1	0.33	0.38	0.43
c2	1.22	-	1.32
D	9.05	9.15	9.25
D1	6.60	-	-
E	10.06	10.16	10.26
E1	7.80	-	8.20
e	2.54(BSC)		
H	14.70	15.10	15.50
L	2.00	2.30	2.60
L1	1.17	1.27	1.40
L2	-	-	1.75
L3	0.25BSC		
L4	2.00REF		
θ	0°	-	8°
θ1	5°	7°	9°
θ2	1°	3°	5°

Mechanical Dimensions
TO-263-2 (Package 2)

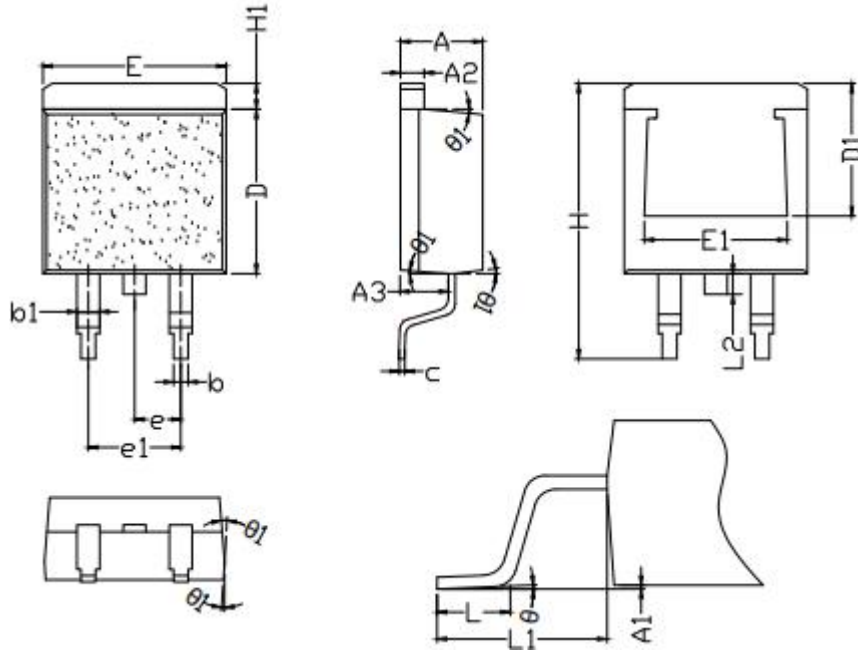
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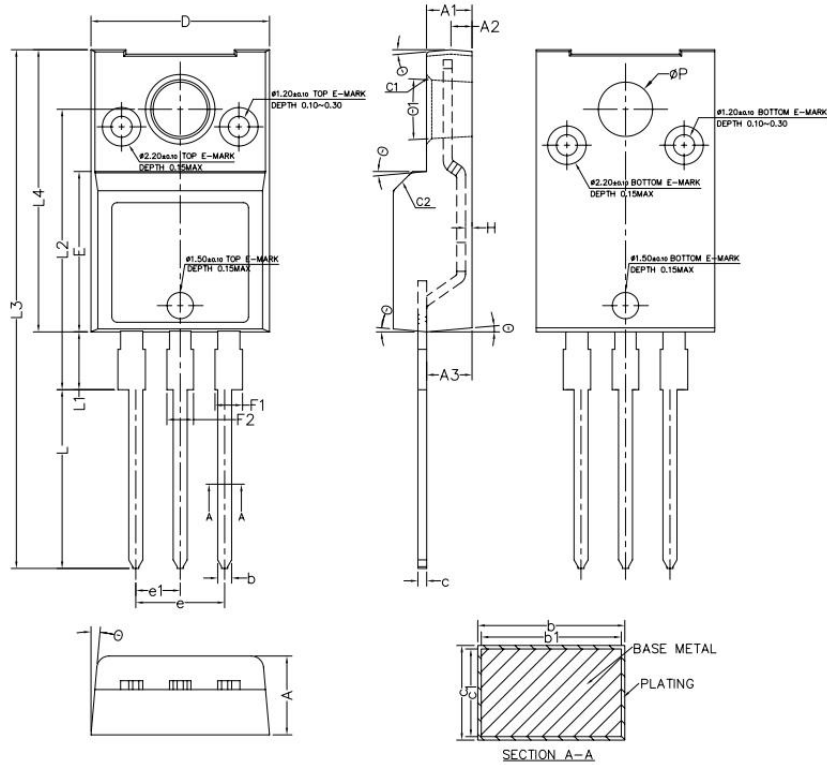
Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.55	4.70	4.85
A1	0.00	0.10	0.25
A2	2.59	2.69	2.89
b	0.71	0.81	0.96
b1	-	1.27	-
c	0.36	0.38	0.61
c1	1.17	1.27	1.37
D	8.55	8.70	8.85
D1	-	7.2	-
E	10.01	10.16	10.31
E1	-	7.80	-
E2	9.98	10.08	10.18
e	-	2.54	-
H	14.70	15.10	15.50
L	2.00	2.30	2.70
L1	1.17	1.27	1.40
L2	-	-	2.20
L3	-	0.25BSC	-
θ	0°	-	8°
θ1		5°	
θ2		4°	
θ3		4°	

Mechanical Dimensions
TO-263-2 (Package 3)

Unit: mm



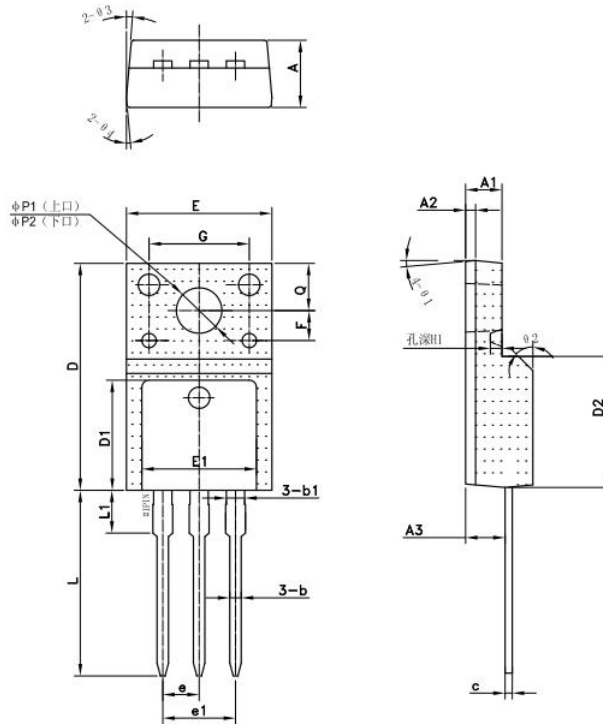
Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.42	4.52	4.62
A1	0.00	0.10	0.25
A2	1.24	1.27	1.32
A3	2.50	2.60	2.70
b	0.77	0.81	0.84
b1	1.23	1.28	1.41
c	0.33	0.38	0.43
D	8.80	8.95	9.10
D1	7.2REF		
E	9.92	10.07	10.22
E1	7.85REF		
e	2.50	2.54	2.58
e1	5.08REF		
H	14.80	15.10	15.30
H1	1.12	1.28	1.42
L	2.10	2.23	2.36
L1	4.55	4.75	4.95
L2	1.10	1.30	1.50
θ	0°	2°	5°
θ1	3°	-	5°

Mechanical Dimensions
TO-220F (Package 1)
Unit: mm


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.40	4.50	4.60
A1	2.50	2.60	2.70
A2	1.10	1.20	1.30
A3	2.49	2.59	2.69
b	0.76	-	0.89
b1	0.75	0.80	0.85
c	0.46	-	0.59
c1	0.45	0.50	0.55
C1	0.20	0.30	0.40
C2	1.00	1.10	1.20
D	10.10	10.20	10.30
E	9.05	9.15	9.25
e	4.98	5.08	5.18
e1	2.44	2.54	2.64
F1	1.22	-	1.60
F2	1.17	-	1.55
H	0.32	0.37	0.42
L	10.00	10.20	10.40
L1	3.15	3.30	3.45
L2	15.85	16.00	16.15
L3	29.30	29.60	29.90
L4	16.00	16.10	16.20
P	3.00	3.10	3.20
θ	3°	5°	7°
θ1	4°	6°	8°

Mechanical Dimensions
TO-220F (Package 2)

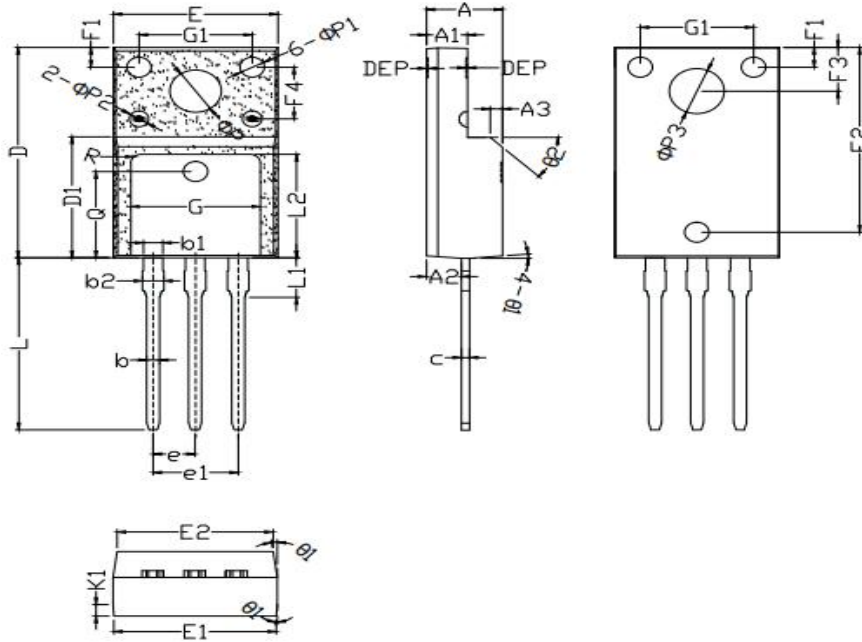
Unit: mm



Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.50	4.70	4.90
A1	2.34	2.54	2.70
A2	-	0.70	-
A3	2.56	2.76	2.96
b	0.70	0.80	0.95
b1	-	1.28	-
c	0.45	0.50	0.65
D	15.67	15.87	16.07
D1	-	7.70	-
D2	-	9.12	-
E	9.96	10.16	10.36
E1	-	8.00	-
e	2.54		
e1	5.08		
F	2.1		
G	7		
H1	-	0.81	-
L	12.48	12.98	13.20
L1	-	2.93	-
ΦP1 (上口)	2.98	3.18	3.38
ΦP2 (下口)	3.20	3.40	3.60
Q	3.10	3.30	3.50
θ1	5°		
θ2	45°		
θ2	5°		
θ3	5°		

Mechanical Dimensions
TO-220F (Package 3)

Unit: mm



Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A2	2.60	2.80	2.95
A3	1.0REF		
b	0.75	0.80	0.85
b1	1.18	1.20	1.24
b2	1.18	1.24	1.30
c	0.45	0.50	0.55
D	15.67	15.87	16.07
D1	9.04	9.12	9.20
E	10.00	10.16	10.30
E1	9.94	10.06	10.30
E2	9.40	9.50	9.60
e	2.50	2.54	2.58
e1	5.08REF		
L	12.78	12.98	13.18
L1	2.70	2.92	3.20
L2	7.70	7.80	7.90
Q	6.50REF		
ΦP	3.08	3.18	3.28
ΦP1	1.45	1.55	1.65
ΦP2	0.95	1.15	1.35
ΦP3	3.30	3.40	3.50
θ1	3°	5°	7°
θ2	42°	45°	48°
F1	1.40	1.50	1.60
F2	13.80	13.90	14.00
F3	3.20	3.30	3.40
F4	3.70	3.90	4.10
G	7.80	8.00	8.20
G1	6.90	7.00	7.10
K1	0.65	0.70	0.75



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